





RF POWER MOSFETs

N-CHANNEL ENHANCEMENT MODE

150V 300W 45MHz

The ARF468A and ARF468B comprise a symmetric pair of common source RF power transistors designed for pushpull scientific, commercial, medical and industrial RF power amplifier applications up to 45 MHz. They have been optimized for both linear and high efficiency classes of operation.

• Specified 150 Volt, 40.68 MHz Characteristics:

Output Power = 300 Watts.

Gain = 15dB (Class AB)

Efficiency = 75% (Class C)

- Low Cost Common Source RF Package.
- Low Vth thermal coefficient.
- Low Thermal Resistance.
- Optimized SOA for Superior Ruggedness.

MAXIMUM RATINGS

All Ratings: $T_C = 25^{\circ}C$ unless otherwise specified.

Symbol	Parameter	Ratings	UNIT	
V _{DSS}	Drain-Source Voltage	500	Volts	
V _{DGO}	Drain-Gate Voltage	500	VOILS	
I _D	Continuous Drain Current @ T _C = 25°C	22	Amps	
V _{GS}	Gate-Source Voltage	±30	Volts	
P _D	Total Power Dissipation @ T _C = 25°C	300	Watts	
R _{eJC}	Junction to Case	0.35	°C/W	
T _J ,T _{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C	
T _L	Lead Temperature: 0.063" from Case for 10 Sec.	300		

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV _{DSS}	Drain-Source Breakdown Voltage ($V_{GS} = 0V$, $I_D = 250 \mu A$)	500			Volts
R _{DS(ON)}	Drain-Source On-State Resistance $(V_{GS} = 10V, I_D = 11A)$			0.3	ohms
I _{DSS}	Zero Gate Voltage Drain Current ($V_{DS} = 500V, V_{GS} = 0V$)			25	μΑ
	Zero Gate Voltage Drain Current ($V_{DS} = 400V$, $V_{GS} = 0V$, $T_{C} = 125$ °C)			250	
I _{GSS}	Gate-Source Leakage Current $(V_{GS} = \pm 30V, V_{DS} = 0V)$			±100	nA
9 _{fs}	Forward Transconductance $(V_{DS} = 25V, I_{D} = 11A)$	5	8	9	mhos
V _{GS} (TH)	Gate Threshold Voltage $(V_{DS} = V_{GS}, I_{D} = 1mA)$	2.5	4	5	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

DYNAMIC CHARACTERISTICS

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C _{iss}	Input Capacitance	V _{GS} = 0V		2230		
C _{oss}	Output Capacitance	V _{DS} = 150V f = 1 MHz		230		pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1/11/12		105		

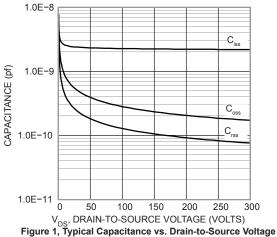
FUNCTIONAL CHARACTERISTICS

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
G _{PS}	Common Source Amplifier Power Gain	f = 40.68 MHz	14	15		dB
η	Drain Efficiency	$V_{GS} = 2.5V$ $V_{DD} = 150V$	70	75		%
Ψ	Electrical Ruggedness VSWR 10:1	P _{out} = 300W	No Degradation in Output Power			Power

⁽¹⁾ Pulse Test: Pulse width < 380µS, Duty Cycle < 2%

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TYPICAL PERFORMANCE CURVES

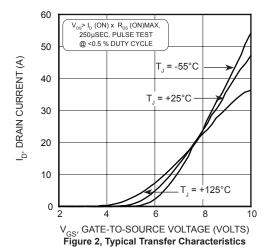


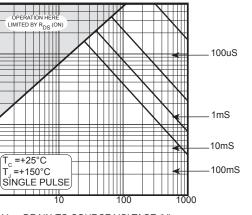
52

T_c =+25°C

=+150°C

ID, DRAIN CURRENT (A)





 $\rm V_{\rm DS},$ DRAIN-TO-SOURCE VOLTAGE (V) Figure 3, Typical Maximum Safe Operating Area

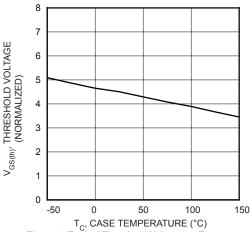
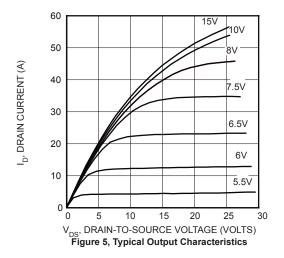
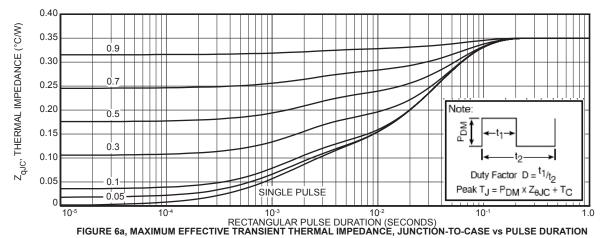


Figure 4, Typical Threshold Voltage vs Temperature





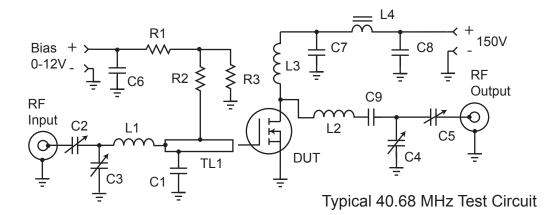
RC MODEL Junction temp(°C) 0.0130 F 0.113 °C/W Power (watts) 0.236 °C/W 0.147 F Case temperature (°C)

Figure 6b, TRANSIENT THERMAL IMPEDANCE

Table 1 - Typical Class AB Large Signal Input - Output Impedance

Freq. (MHz)	$Z_{in}(\Omega)$	$Z_{OL}(\Omega)$
2.0	18 - j 10.5	21 - j 1.4
13.5	2.7 - j 4.6	17.5 - j 7.8
27.1	1.8 - j 1.6	11.7 - j 10.4
40.7	1.7 - j 0.2	7.7 - j 10

 $Z_{_{IN}}$ - Gate shunted with 25 Ω I $_{_{dq}}$ = 0 $Z_{_{OL}}$ - Conjugate of optimum load for 300 Watts output at V $_{_{dd}}$ =125V



C1 -- 2200pF ATC 700B C2-C5 -- Arco 465 Mica trimmer C6-C8 -- .1 µF 500V ceramic chip C9 -- 3x 2200 pF 500V chips COG L1 -- 4t #22 AWG .25"ID .25 "L ~87nH L2 -- 5t #16 AWG .312" ID .35"L ~176nH

L3 -- 10t #24 AWG .25"ID ~.5μH L4 -- VK200-4B ferrite choke 3μH R1- R3 -- $1k\Omega$ 0.5 Ω Carbon TL1 -- 34Ω t-line 0.175" x 1" C1 .45" from gate pin. PCB -- 0.062" FR4, Er=4.7

TO-264 (L) Package Outline Dimensions in Millimeters and (Inches) NOTE: These two parts comprise a symmetric pair of RF 5.79 (.228) 6.20 (.244) power transistors and meet the same electrical specifications. The device pin-outs are the mirror image of each other to allow ease of use as a push-pull pair. Drain 25.48 (1.003) 26.49 (1.043) Device 2.29 (.090) 2.69 (.106) ARF - A ARF - B 19.81 (.780) 21.39 (.842) Gate Drain Source Source Drain Gate 0.76 (.030) 1.30 (.051) 2.79 (.110) 3.18 (.125) 5.45 (.215) BSC

Dimensions in Millimeters and (Inches)

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